

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning at page 8, line 17, with the following rewritten paragraph:

The organic solvent used for preparing the organic silicate polymer of the present invention may comprise a mixture of silane, water and catalyst or any organic solvent as long as the solvent does not restrict hydrolysis and condensation in phase-separated state. Examples of such organic solvent are aliphatic hydrocarbon solvent like n-pentane, i-pentane, n-hexane, i-hexane, 2,2,4-trimethylpentane, cyclohexane or methylcyclohexane; aromatic hydrocarbon solvents like benzene, toluene, xylene, trimethylbenzene, ethylbenzene or methylethylbenzene; alcoholic solvents like methyl alcohol, ethyl alcohol, n-propanol, i-propanol, n-butanol, i-butanol, sec-butanol, t-butanol, 4-methyl 2-pentanone, cyclohexanol, methylcyclohexanol or glycerol; ketonic solvents like acetone, methyl ethyl ketone, methyl-n-propyl ketone, methyl-n-butyl ketone, methyl-i-butyl ketone, diethyl ketone, cyclohexanone, methylcyclohexanone or acetylacetone ethereal solvents like tetrahydrofuran, 2-methyltetrahydrofuran, ethyl ether, n-propyl ether, i-propyl ether, n-butyl ether, ~~diglyme~~, dioxin, dimethyldioxin, ethylene glycol monomethyl ether, ethylene glycol monoethyl ether, ethylene glycol-n-propyl ether, ethylene glycol dimethyl ether, ethylene glycol diethyl ether, propyleneglycol monomethyl ether, propyleneglycol monoethyl ether, propyleneglycol monopropyl ether, propyleneglycol dimethyl ether, propyleneglycol diethyl ether or propyleneglycol dipropyl ether; ester solvents like diethyl carbonate, methyl acetate, ethyl acetate, n-propyl acetate, i-propyl acetate, n-butyl acetate, ethyl lactate, ethylene glycol monomethyl ether acetate, ethylene glycol monoethyl ether acetate, propyleneglycol monomethyl ether acetate, propyleneglycol monoethyl ether acetate, propyleneglycol monopropyl ether acetate, ethylene glycol diacetate or propyleneglycol diacetate; and amide solvents like N-methylpyrrolidone, formamide, N-methylformamide, N-ethylformamide, N,N-dimethylformamide, N,N~diethylformamide, N-methylacetamide, N-ethylacetamide, N,N-dimethylacetamide or N,N-diethylacetamide.

Please replace the paragraph beginning at page 14, line 1, with the following rewritten paragraph:

After the drying and hardening processes, surface treatment may be carried out to minimize hydroxy groups of the insulation film, if required. The surface treatment can be carried out using a silyl compound like hexamethyl disilazane, alkyl-alkoxy silane or alkyi-acetoxy silane or in reduction gas like hydrogen or in fluorine-containing gas. Silylation of the insulation film can be carried out as follows. The insulation film is dipped or spin-coated with silyl compound, which may be diluted with solvent, or silylated in silyl compound vapor. After silylation, the insulation film may be heated to the temperature of about 100°C to about 400°C.

Please replace the paragraph beginning at page 15, line 3, with the following rewritten paragraph:

(Oxidation of hydrosilane)

15g of distilled water, 30g of tetrahydrofuran and 500mg of Pd/C (10%) powder were mixed in a reaction chamber and the temperature of the chamber was maintained at 0°C. 10g of tetramethylcyclotetrasiloxane was slowly added to this solution and the reaction chamber was let alone overnight. After the reaction was completed, the solution was filtered to remove the metal catalyst. Then, the organic solvent was removed in vacuum to obtain 19g of oxidized hydrosiloxane containing 11 g of tetraethyltetrahydroxy tetramethyl cyclotetrasiloxane.